

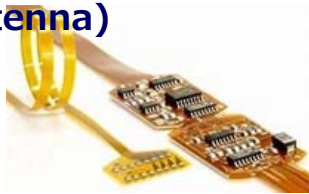


—Low Df—

“Modified-PI(MPI) based FCCL”

Example of use

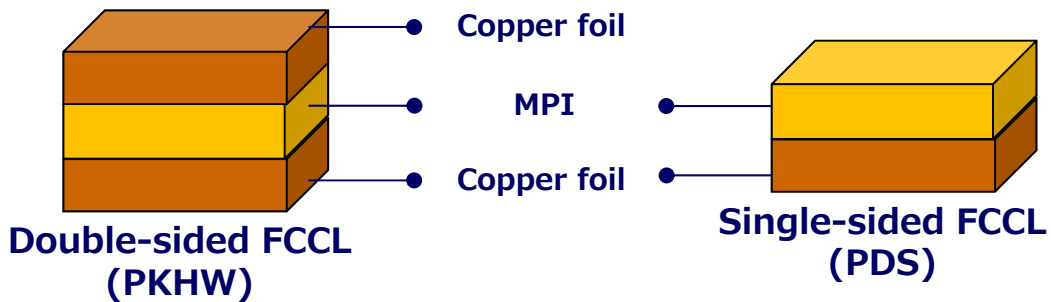
- Flexible substrate for high speed data transmission (for antenna)



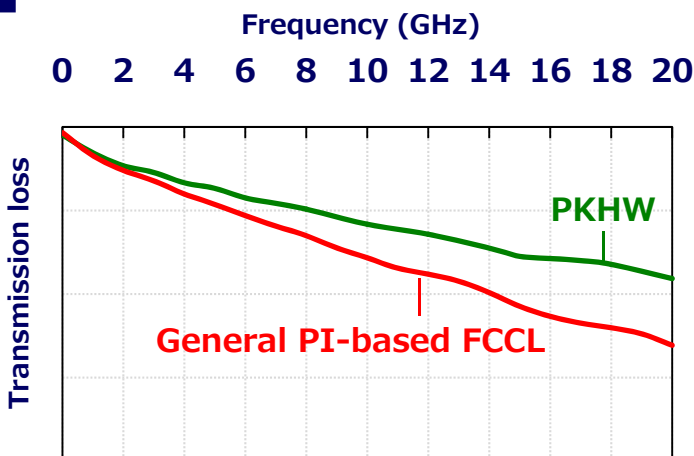
Characteristics

- Top-class performance in dielectric property (Df) and water absorption among polyimide-based FCCL
- High heat resistance which is durable to reflow process. Suitable for SMT(surface mount technology).
- Excellent flexibility. Applicable to the area requires durability to repetitive bending.

Product structure



Product Properties



Circuit : Micro-strip patterning
 Impedance : 50±5Ω (designed)
 Test environment : 23℃, 50%RH
 Insulation layer thickness : 50μm
 Cu thickness : 12μm
 Circuit length : 100mm

Item	Unit	PKHW	PDS
Dk	-	3.50	3.30
Df	-	0.003	0.003
Water absorption	wt%	0.7	0.7
90° Peel strength	N/cm	12.0	10.0
Solder heat resistance	℃	340<	340<



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